

ABSTRACT

An object of the present invention is to provide a thermosetting resin sheet in which variation in the resin composition does not occur even at the time of resin sealing in a large area and with which an electronic component package having a high quality can be stably fabricated, as well as a method for manufacturing an electronic component package using this. The present invention relates to a thermosetting resin sheet containing an inorganic filler and being in a B-stage state with a projected area of 31400 mm^2 or more as viewed in a plan view.